

16 A, 600 V, low drop IGBT

## Features

- Low on-voltage drop ( $V_{CE(sat)}$ )
- High current capability

## Applications

- Light dimmer
- Static relays
- Motor drive

## Description

This IGBT utilizes the advanced PowerMESH™ process featuring extremely low on-state voltage drop in low-frequency working conditions (up to 1 kHz).

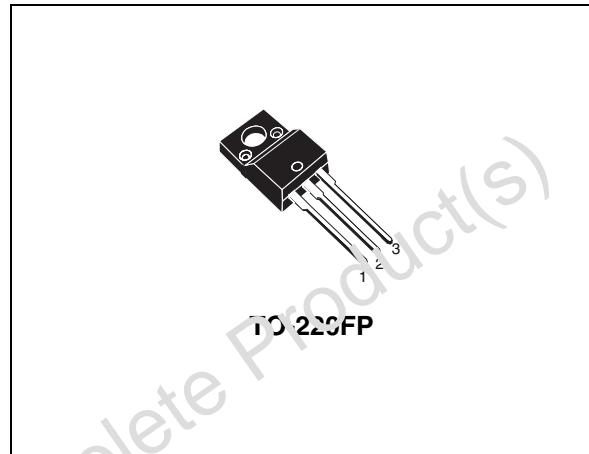


Figure 1. Internal schematic diagram

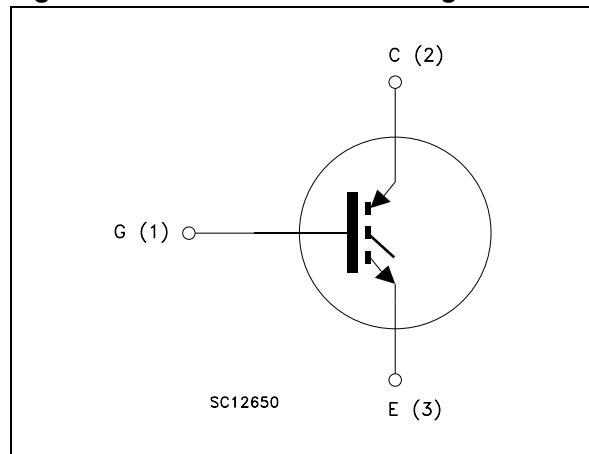


Table 1. Device summary

Order codes	Marking	Package	Packaging
STGP10NB60SFP	GP10NB60SFP	TO-220-FP	Tube

# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-emitter voltage ( $V_{GE} = 0$ )	600	V
$I_C^{(1)}$	Continuous collector current at $T_C = 25^\circ\text{C}$	23	A
$I_C^{(1)}$	Continuous collector current at $T_C = 100^\circ\text{C}$	12	A
$I_{CL}^{(2)}$	Turn-off latching current	20	A
$I_{CP}^{(3)}$	Pulsed collector current	80	A
$V_{GE}$	Gate-emitter voltage	$\pm 20$	V
$V_{ISO}$	Isolation withstand voltage (RMS) from all three leads to external heat sink ( $t=1\text{ s}$ ; $T_C = 25^\circ\text{C}$ )	2500	V
$P_{TOT}$	Total dissipation at $T_C = 25^\circ\text{C}$	25	W
$T_j$	Operating junction temperature	-55 to 150	$^\circ\text{C}$

1. Calculated according to the iterative formula:

$$I_C(T_C) = \frac{T_{j(\max)} - T_C}{R_{thj-c} \times V_{CE(sat)(\max)}(T_{j(\max)}, I_C(T_C))}$$

2.  $V_{clamp} = 80\%$  of  $V_{CES}$ ,  $T_j = 150^\circ\text{C}$ ,  $R_G = 1\text{k}\Omega$ ,  $V_{GE} = 15\text{ V}$

3. Pulse width limited by maximum junction temperature and turn-off within RBSOA

**Table 3. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	5	$^\circ\text{C/W}$
$R_{thj-amb}$	Thermal resistance junction-ambient	62.5	$^\circ\text{C/W}$

## 2 Electrical characteristics

( $T_j = 25^\circ\text{C}$  unless otherwise specified)

**Table 4. Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{CES}}$	Collector-emitter breakdown voltage ( $V_{\text{GE}} = 0$ )	$I_C = 250 \mu\text{A}$	600			V
$V_{(\text{BR})\text{ECS}}$	Emitter-collector breakdown voltage ( $V_{\text{GE}} = 0$ )	$I_C = 1 \text{ mA}$	20			V
$I_{\text{GES}}$	Gate-emitter leakage current ( $V_{\text{CE}} = 0$ )	$V_{\text{GE}} = \pm 20 \text{ V}$			$\leq 100$	nA
$I_{\text{CES}}$	Collector cut-off current ( $V_{\text{GE}} = 0$ )	$V_{\text{CE}} = 600 \text{ V}$ $V_{\text{CE}} = 600 \text{ V}, T_j = 125^\circ\text{C}$			10 100	$\mu\text{A}$ $\mu\text{A}$
$V_{\text{GE}(\text{th})}$	Gate threshold voltage	$V_{\text{CE}} = V_{\text{GE}}, I_C = 250 \mu\text{A}$	2.5		5	V
$V_{\text{CE}(\text{sat})}$	Collector-emitter saturation voltage	$V_{\text{GE}} = 15 \text{ V}, I_C = 5 \text{ A}$ $V_{\text{GE}} = 15 \text{ V}, I_C = 10 \text{ A}$ $V_{\text{GE}} = 15 \text{ V}, I_C = 10 \text{ A}, T_j = 125^\circ\text{C}$		1.15 1.35 1.25	1.75	V
$g_{\text{fs}}^{(1)}$	Forward transconductance	$V_{\text{CE}} = 15 \text{ V}, I_C = 10 \text{ A}$	5			S

1. Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{\text{ies}}$ $C_{\text{oes}}$ $C_{\text{res}}$	Input capacitance Output capacitance Reverse transfer capacitance	$V_{\text{CE}} = 25 \text{ V}, f = 1 \text{ MHz}, V_{\text{GE}} = 0$	-	610 65 12	-	pF pF pF
$Q_g$	Total gate charge	$V_{\text{CE}} = 400 \text{ V}, I_C = 10 \text{ A}, V_{\text{GE}} = 15 \text{ V}$ (see Figure 17)	-	33	-	nC

**Table 6. Switching on/off (inductive load)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ $t_r$ $(di/dt)_{on}$	Turn-on delay time Current rise time Turn-on current slope	$V_{CC} = 480 \text{ V}$ , $I_C = 10 \text{ A}$ $R_G = 1 \text{ k}\Omega$ , $V_{GE} = 15 \text{ V}$ (see Figure 16)	-	0.7 0.46 8	-	$\mu\text{s}$ $\mu\text{s}$ $\text{A}/\mu\text{s}$
$t_r(V_{off})$ $t_d(off)$ $t_f$	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 480 \text{ V}$ , $I_C = 10 \text{ A}$ $R_G = 1 \text{ k}\Omega$ , $V_{GE} = 15 \text{ V}$ (see Figure 16)	-	2.2 1.2 1.2	-	$\mu\text{s}$
$t_r(V_{off})$ $t_d(off)$ $t_f$	Off voltage rise time Turn-off delay time Current fall time	$V_{CC} = 480 \text{ V}$ , $I_C = 10 \text{ A}$ $R_G = 1 \text{ k}\Omega$ , $V_{GE} = 15 \text{ V}$ , $T_j = 125^\circ\text{C}$ (see Figure 16)	-	3.8 1.2 1.9	-	$\mu\text{s}$

**Table 7. Switching energy (inductive load)**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$E_{on}^{(1)}$ $E_{off}^{(2)}$ $E_{ts}$	Turn-on switching losses Turn-off switching losses Total switching losses	$V_{CC} = 480 \text{ V}$ , $I_C = 10 \text{ A}$ $R_G = 1 \text{ k}\Omega$ , $V_{GE} = 15 \text{ V}$ (see Figure 16)	-	0.6 5 5.6	-	$\mu\text{J}$ $\mu\text{J}$ $\mu\text{J}$
$E_{off}^{(2)}$	Turn-off switching losses	$V_{CC} = 480 \text{ V}$ , $I_C = 10 \text{ A}$ $R_G = 1 \text{ k}\Omega$ , $V_{GE} = 15 \text{ V}$ , $T_j = 125^\circ\text{C}$ (see Figure 16)	-	8	-	$\mu\text{J}$

1.  $E_{on}$  is the turn-on losses when a typical diode is used in the test circuit. If the IGBT is offered in a package with a co-pack diode, the co-pack diode is used as external diode. IGBTs and diode are at the same temperature ( $25^\circ\text{C}$  and  $125^\circ\text{C}$ ).
2. Turn-off losses include also the tail of the collector current.

## 2.1 Electrical characteristics (curves)

Figure 2. Output characteristics

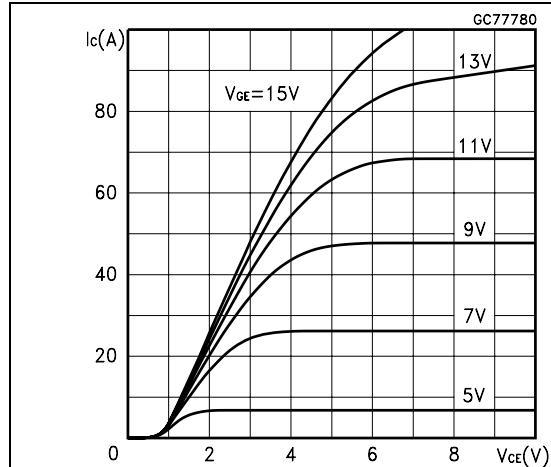


Figure 3. Transfer characteristics

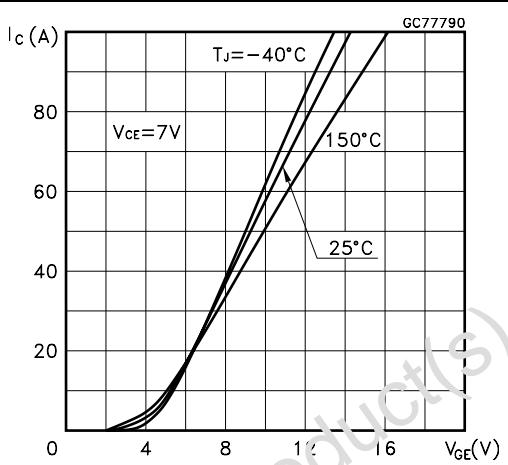


Figure 4. Transconductance

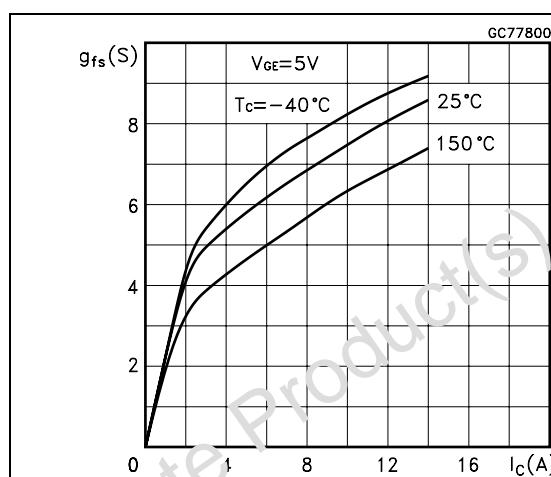


Figure 5. Collector-emitter on voltage vs temperature

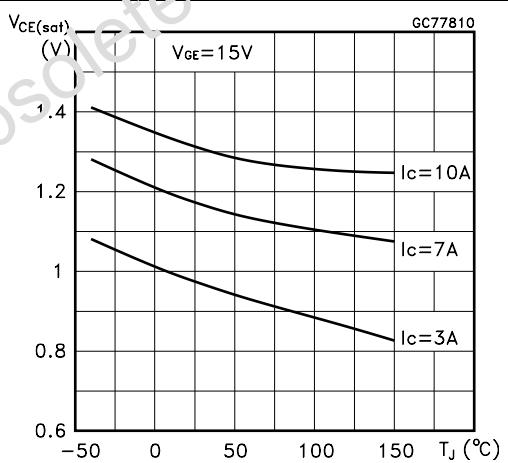


Figure 6. Collector-emitter on voltage vs collector current

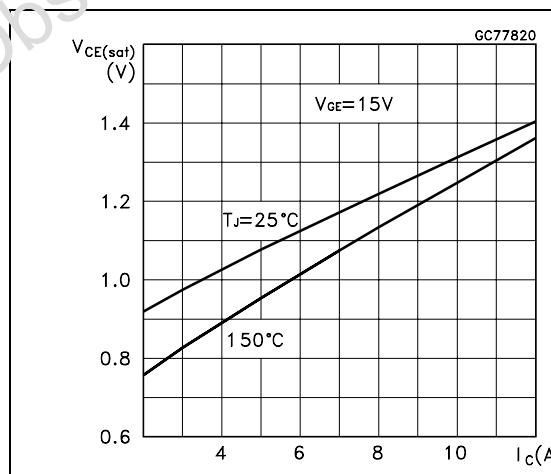
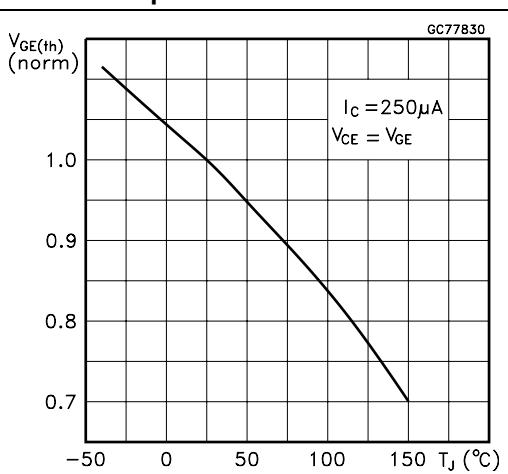
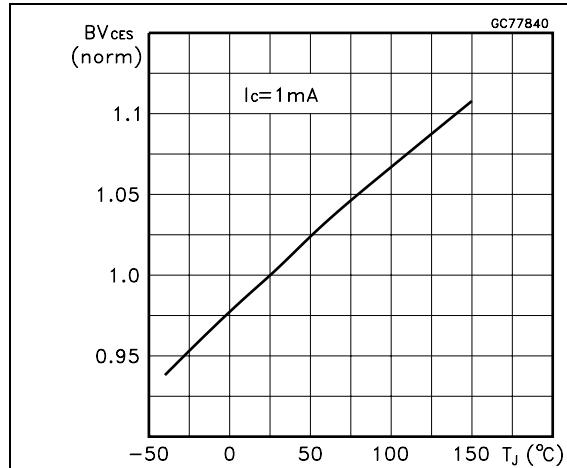
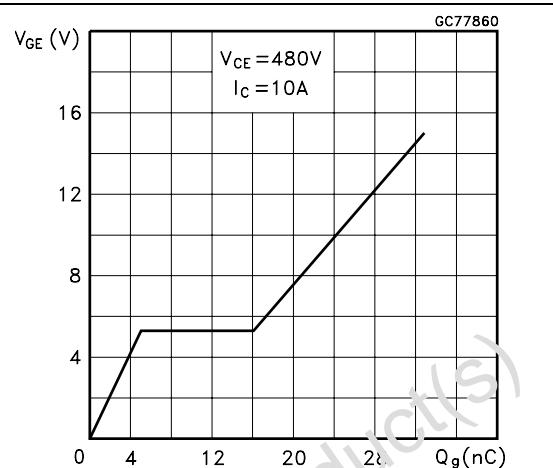
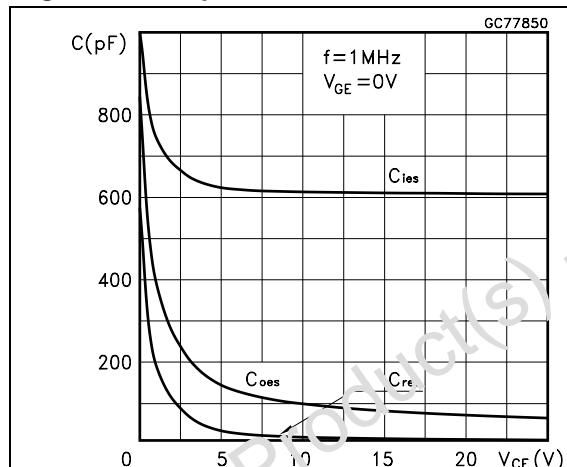
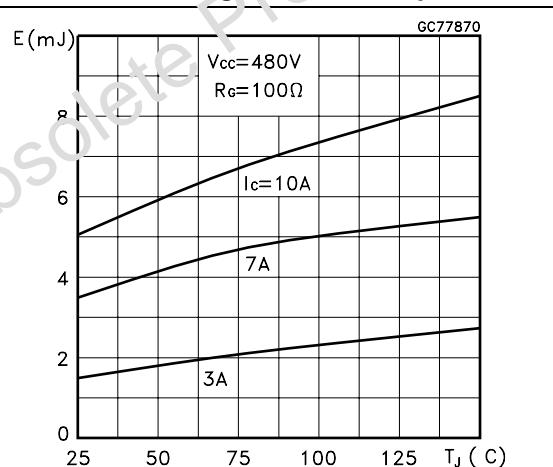
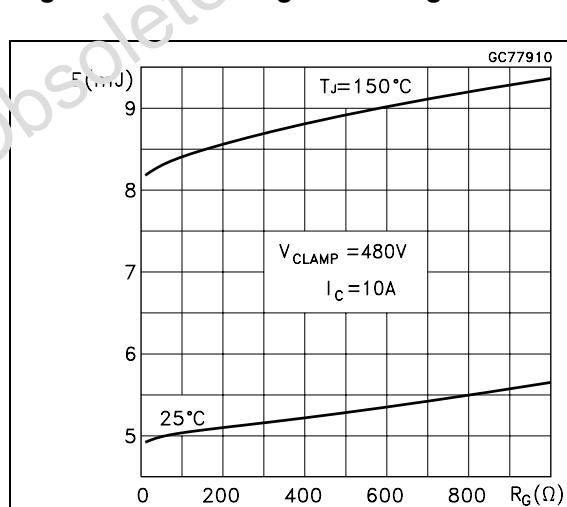
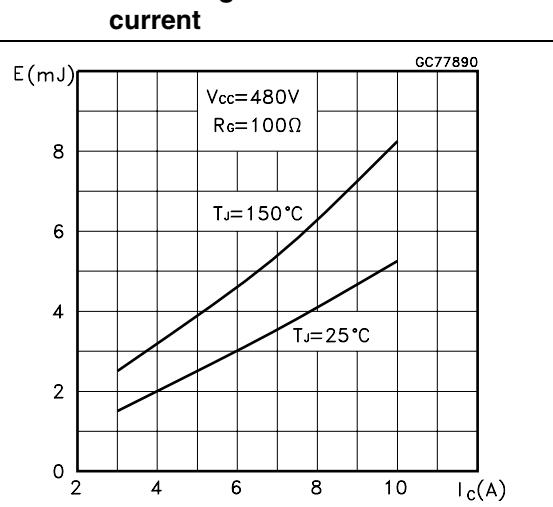
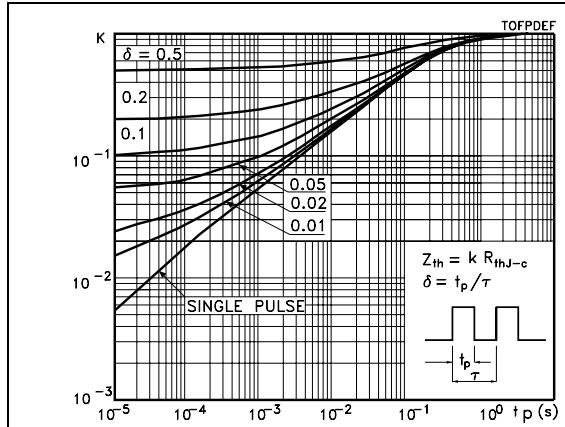
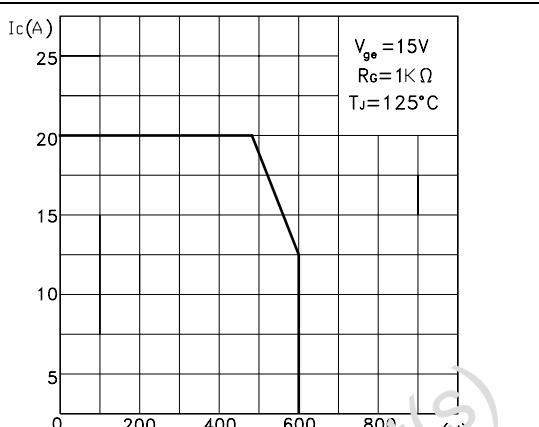


Figure 7. Normalized gate threshold vs temperature

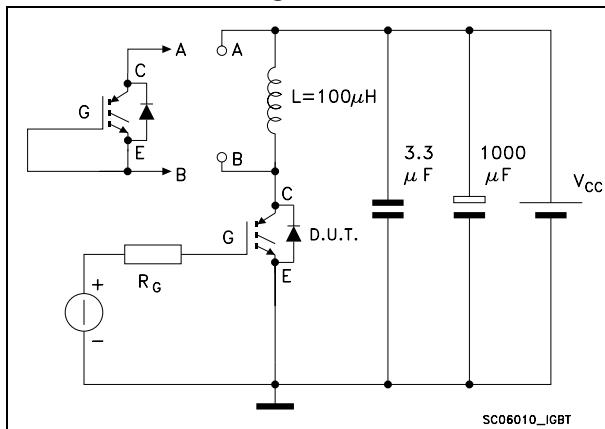


**Figure 8. Normalized breakdown voltage vs temperature****Figure 9. Gate charge vs gate-emitter voltage****Figure 10. Capacitance variations****Figure 11. Switching losses vs temperature****Figure 12. Switching losses vs gate resistance****Figure 13. Switching losses vs collector current**

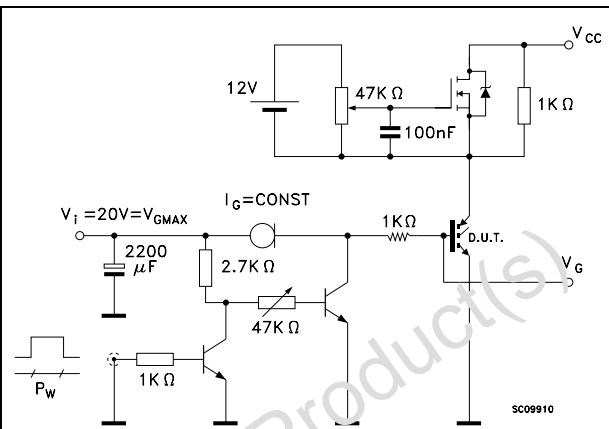
**Figure 14. Thermal impedance****Figure 15. Turn-off SOA**

## 3 Test circuits

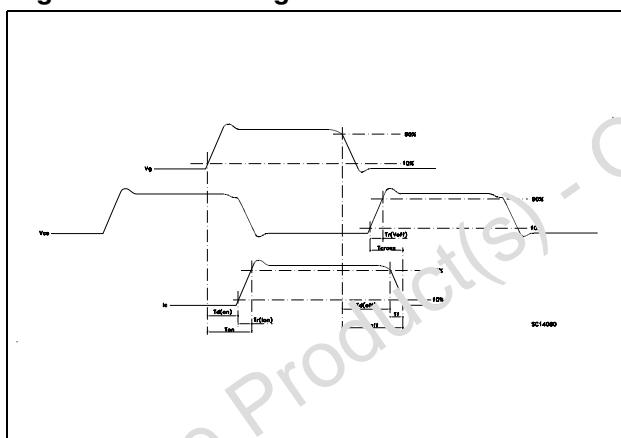
**Figure 16.** Test circuit for inductive load switching



**Figure 17. Gate charge test circuit**



**Figure 18. Switching waveforms**

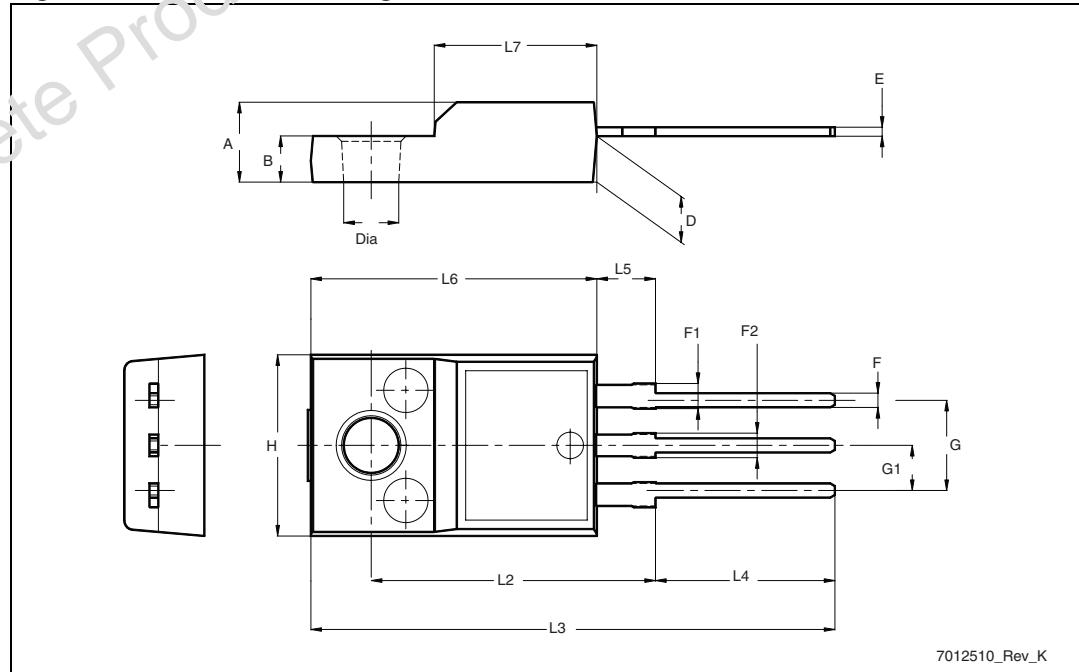


## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com).  
ECOPACK is an ST trademark.

**Table 8.** TO-220FP mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

**Figure 19.** TC-220FP drawing

## 5 Revision history

**Table 9. Document revision history**

Date	Revision	Changes
03-Oct-2011	1	New release.

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